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IXYS Corporation
IXTC220N055T

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EIS electronic components
Distributor of IXYS Corporation: Excellent Integrated System Limited
Datasheet of IXTC220N055T - MOSFET N-CH 55V 130A ISOPLUS220
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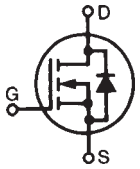
Preliminary Technical Information

TrenchMV™ Power MOSFET
(Electrically Isolated Back Surface)

IXTC220N055T

V_{DSS} = 55 V
I_{D25} = 130 A
$R_{DS(on)}$ ≤ 4.4 mΩ

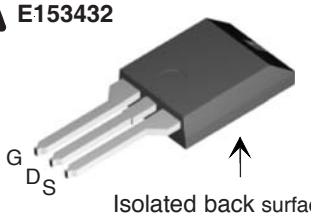
N-Channel Enhancement Mode
Avalanche Rated



Symbol	Test Conditions	Maximum Ratings	
V_{DSS}	T_J = 25°C to 175°C	55	V
V_{DGR}	T_J = 25°C to 175°C; R_{GS} = 1 MΩ	55	V
V_{GSM}	Transient	± 20	V
I_{D25}	T_C = 25°C	130	A
I_{LRMS}	Package Current Limit, RMS	75	A
I_{DM}	T_C = 25°C, pulse width limited by T_{JM}	600	A
I_{AR}	T_C = 25°C	25	A
E_{AS}	T_C = 25°C	500	mJ
dv/dt	$I_S \le I_{DM}$, di/dt ≤ 100 A/μs, $V_{DD} \le V_{DSS}$ $T_J \le 175°C$, R_G = 5 Ω	3	V/ns
P_D	T_C = 25°C	150	W
T_J		-55 ... +175	°C
T_{JM}		175	°C
T_{stg}		-55 ... +175	°C
T_L	1.6 mm (0.062 in.) from case for 10 s	300	°C
T_{SOLD}	Plastic body for 10 seconds	260	°C
V_{ISOL}	50/60 Hz, t = 1 minute, I_{ISOL} < 1 mA, RMS	2500	V
F_C	Mounting force	11..65/2.5..15	N/lb.
Weight		2	g

Symbol	Test Conditions (T_J = 25°C unless otherwise specified)	Characteristic Values Min.	Typ.	Max.	
BV_{DSS}	V_{GS} = 0 V, I_D = 250 μA	55			V
$V_{GS(th)}$	$V_{DS} = V_{GS}$, I_D = 250 μA	2.0		4.0	V
I_{GSS}	V_{GS} = ± 20 V, V_{DS} = 0 V			± 200	nA
I_{DSS}	$V_{DS} = V_{DSS}$ V_{GS} = 0 V T_J = 150°C			5 250	μA μA
$R_{DS(on)}$	V_{GS} = 10 V, I_D = 25 A, Note 1		3.4	4.4	mΩ

ISOPLUS220 (IXTC)
E153432



Isolated back surface

G = Gate D = Drain
S = Source

Features
- Ultra-low On Resistance
- Unclamped Inductive Switching (UIS) rated
- Low package inductance
  - easy to drive and to protect
- 175 °C Operating Temperature

Advantages
- Easy to mount
- Space savings
- High power density

Applications
- Automotive
  - Motor Drives
  - High Side Switch
  - 12V Battery
  - ABS Systems
- DC/DC Converters and Off-line UPS
- Primary- Side Switch
- High Current Switching Applications

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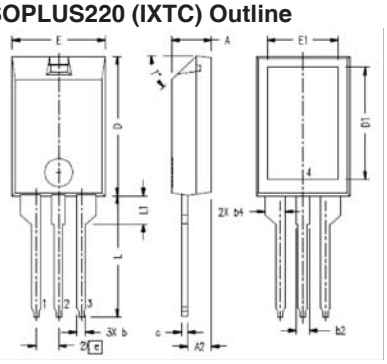
Symbol	Test Conditions (T_J = 25°C unless otherwise specified)	Characteristic Values Min.	Typ.	Max.	
g_{fs}	V_{DS} = 10 V, I_D = 60 A, Note 1	75	120		S
C_{iss}			7200		pF
C_{oss}	V_{GS} = 0 V, V_{DS} = 25 V, f = 1 MHz		1270		pF
C_{rss}			285		pF
$t_{d(on)}$			36		ns
t_r	V_{GS} = 10 V, V_{DS} = 0.5 V_{DSS}, I_D = 25 A		62		ns
$t_{d(off)}$	R_G = 5 Ω (External)		53		ns
t_f			53		ns
$Q_{g(on)}$			158		nC
Q_{gs}	V_{GS}= 10 V, V_{DS} = 0.5 V_{DSS}, I_D = 25 A		42		nC
Q_{gd}			46		nC
R_{thJC}				1.0	°C/W
R_{thCS}			0.25		°C/W

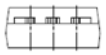
Source-Drain Diode

Symbol	Test Conditions (T_J = 25°C unless otherwise specified)	Characteristic Values Min.	Typ.	Max.	
I_S	V_{GS} = 0 V			220	A
I_{SM}	Pulse width limited by T_{JM}			600	A
V_{SD}	I_F = 25 A, V_{GS} = 0 V, Note 1			1.0	V
t_{rr}	I_F = 25 A, -di/dt = 100 A/μs V_R = 30 V, V_{GS} = 0 V		30		ns

Notes: 1. Pulse test, t ≤ 300 μs, duty cycle d ≤ 2 %;
2. Drain and Source Kelvin contacts must be located less than 5 mm from the plastic body.

ISOPLUS220 (IXTC) Outline





1.Gate 2. Drain
3.Source

Note: Bottom heatsink (Pin 4) is electrically isolated from Pins 1,2, and 3.

SYM	INCHES MIN	INCHES MAX	MILLIMETERS MIN	MILLIMETERS MAX
A	.157	.197	4.00	5.00
A2	.098	.118	2.50	3.00
b	.035	.051	0.90	1.30
b2	.049	.065	1.25	1.65
b4	.093	.100	2.35	2.55
c	.028	.039	0.70	1.00
D	.591	.630	15.00	16.00
D1	.472	.512	12.00	13.00
E	.394	.433	10.00	11.00
E1	.295	.335	7.50	8.50
e	.100 BASIC		2.55 BASIC	
L	.512	.571	13.00	14.50
L1	.118	.138	3.00	3.50
T°			42.5°	47.5°

PRELIMINARY TECHNICAL INFORMATION

The product presented herein is under development. The Technical Specifications offered are derived from data gathered during objective characterizations of preliminary engineering lots; but also may yet contain some information supplied during a pre-production design evaluation. IXYS reserves the right to change limits, test conditions, and dimensions without notice.

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IXYS MOSFETs and IGBTs are covered by one or moreof the following U.S. patents: 4,835,592 4,850,072 4,881,106 4,931,844 5,017,508 5,034,796 5,049,961 5,063,307 5,187,117 5,237,481 5,381,025 5,486,715 6,162,665 6,259,123 B1 6,306,728 B1 6,404,065 B1 6,534,343 6,583,505 6,683,344 6,710,405B2 6,710,463 6,727,585 6,759,692 6771478 B2 7,005,734 B2 7,063,975 B2 7,071,537

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Fig. 1. Output Characteristics @ 25ºC

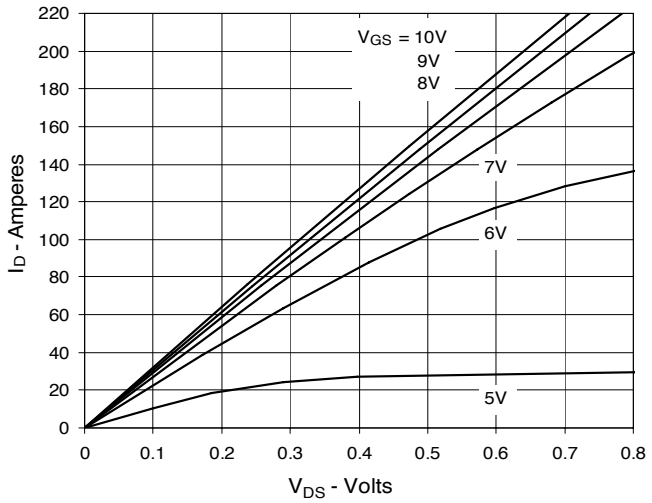

Fig. 2. Extended Output Characteristics @ 25ºC

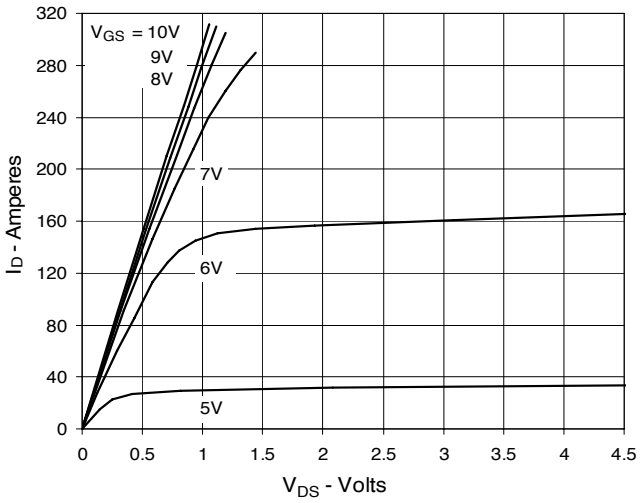

Fig. 3. Output Characteristics @ 150ºC

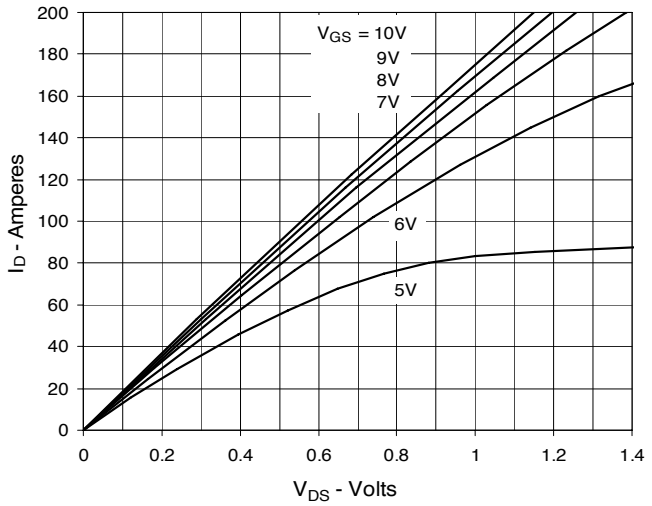

Fig. 4. $R_{DS(on)}$ Normalized to I_D = 110A Value vs. Junction Temperature

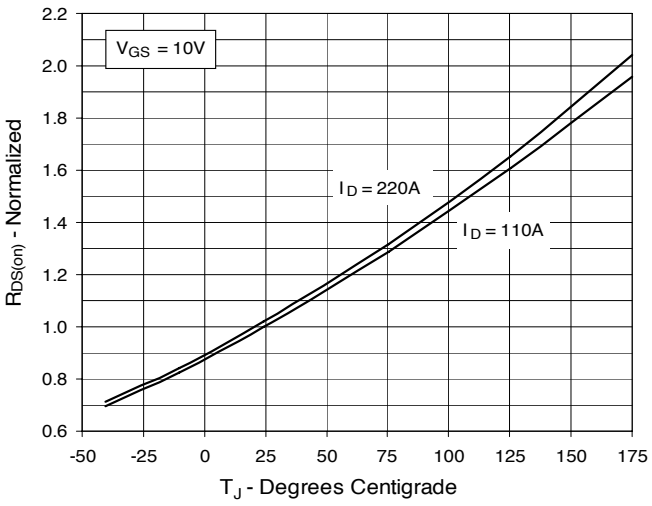

Fig. 5. $R_{DS(on)}$ Normalized to I_D = 110A Value vs. Drain Current

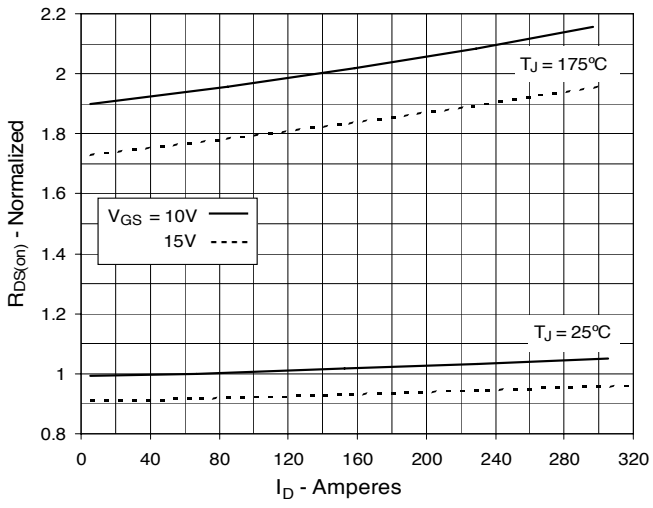

Fig. 6. Drain Current vs. Case Temperature

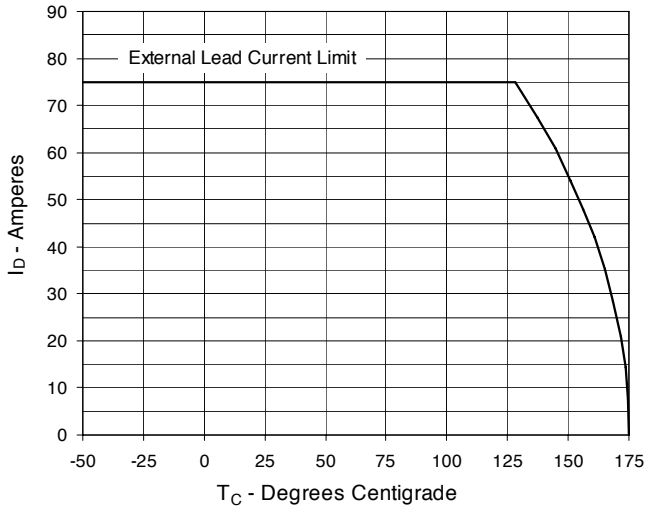

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Fig. 7. Input Admittance

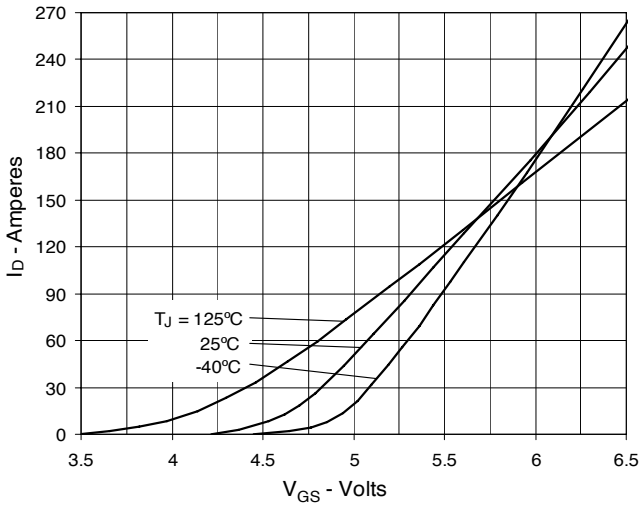

Fig. 8. Transconductance

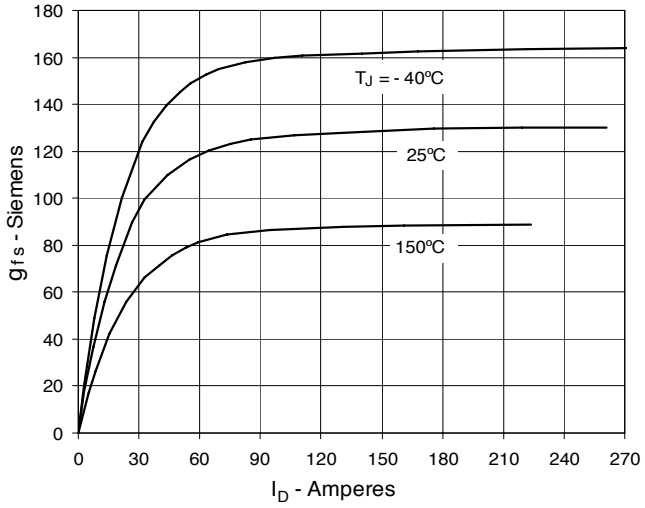

Fig. 9. Forward Voltage Drop of Intrinsic Diode

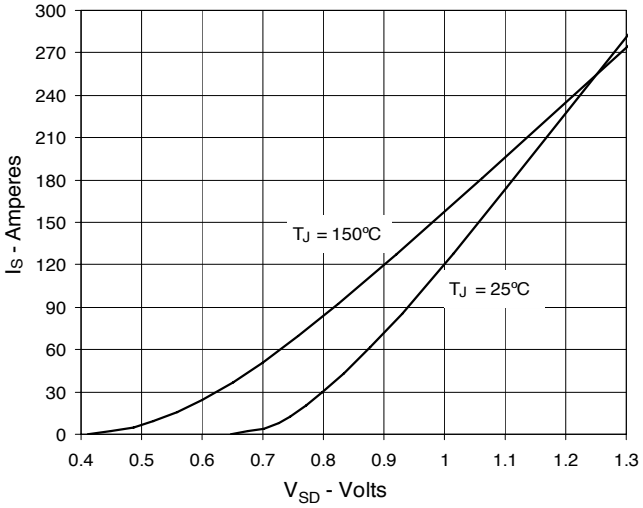

Fig. 10. Gate Charge

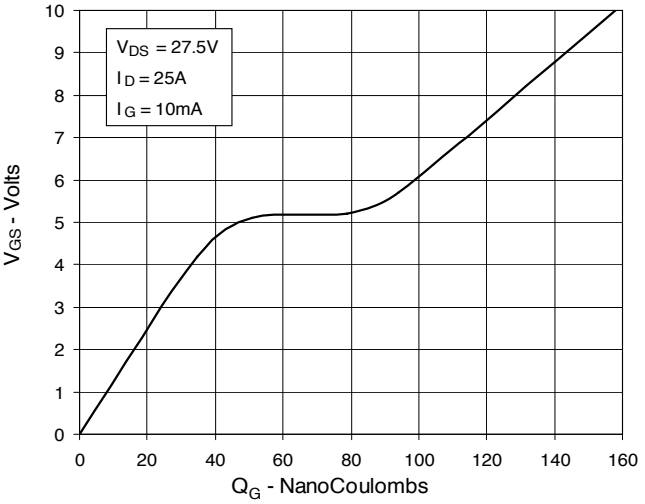

Fig. 11. Capacitance

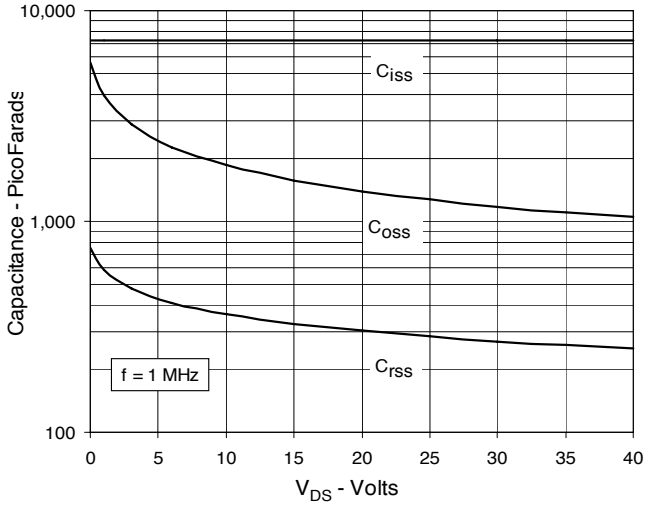

Fig. 12. Maximum Transient Thermal Impedance

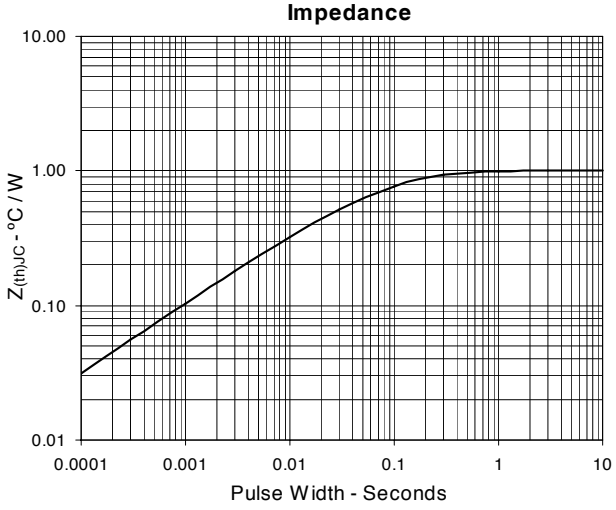

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Fig. 13. Resistive Turn-on Rise Time vs. Junction Temperature

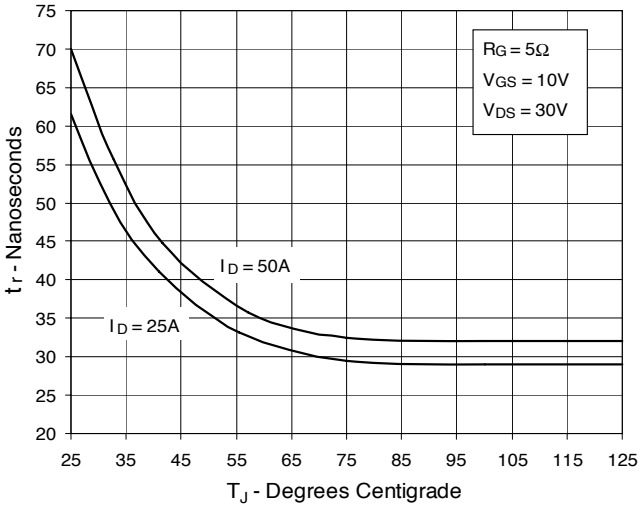


Fig. 14. Resistive Turn-on Rise Time vs. Drain Current

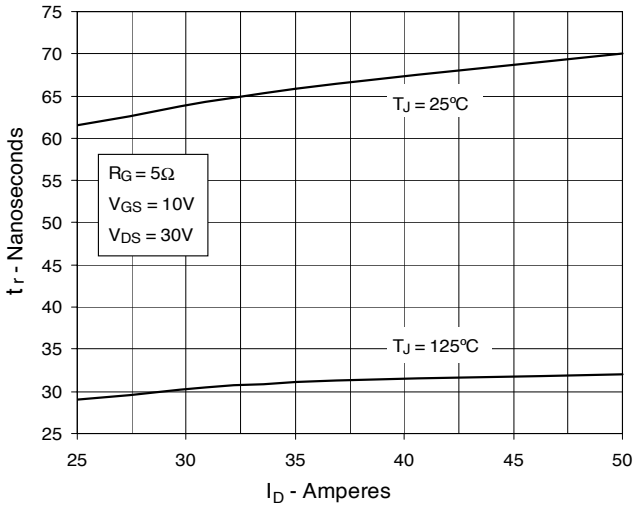


Fig. 15. Resistive Turn-on Switching Times vs. Gate Resistance

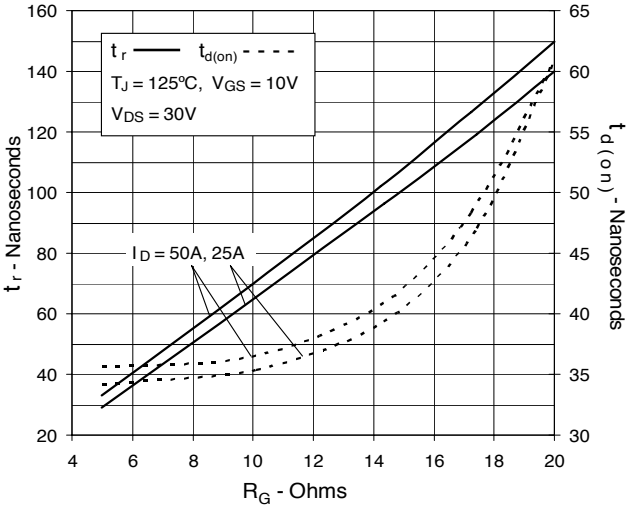


Fig. 16. Resistive Turn-off Switching Times vs. Junction Temperature

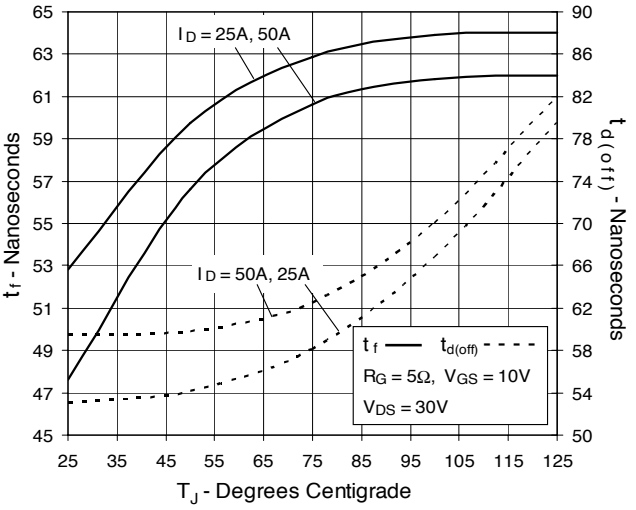


Fig. 17. Resistive Turn-off Switching Times vs. Drain Current

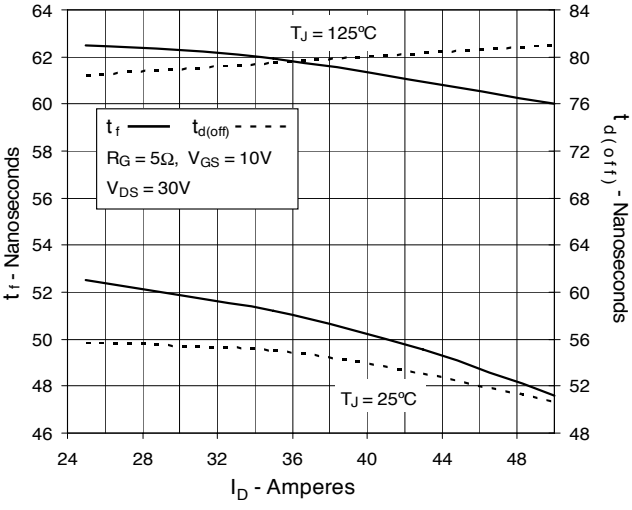
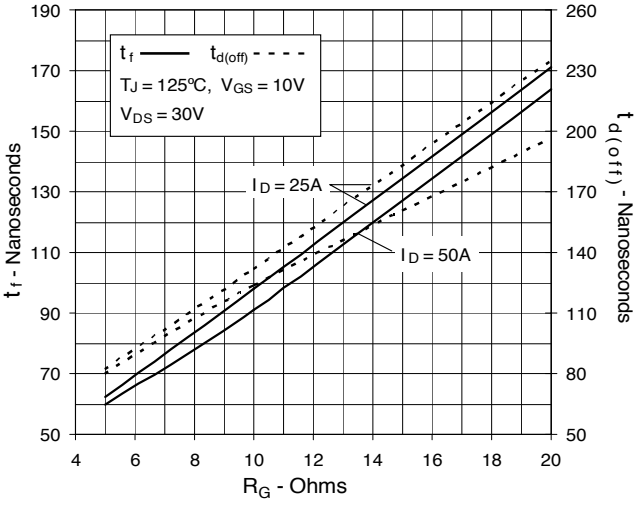


Fig. 18. Resistive Turn-off Switching Times vs. Gate Resistance



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